nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier | | User Part Number | | | | | | |
|--|-----------------------------|---|-------------|-----------|------------|-----------|--|--|
| Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | PDTA113EMB Part Description | | | | | | |
| | | | | | | | | |
| | | MCD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | | | TEST | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | | | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 464 | 20960 | 0 | | |
| | | MIL-STD-750-1 | | | | | | |
| | HTRB | M1039 Method A | | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 415 | 18680 | 0 | | |
| | - | 150000 4104 | | | | | | |
| | TC Temperature Cycling | JESD22-A104 -65 °C to Timax, not to exceed 150°C | 1000 | | 53.40 | • | | |
| # A4 | Temperature Cycling | -65 °C to Tjillax, not to exceed 150°C | 1000 cycles | 116 | 5240 | 0 | | |
| | UHAST | JESD22-A118 | | | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | | 116 | 5240 | 0 | | |
| | | JESD22-A102 | — 96 hours | | | | | |
| | AC | Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$ | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | | | |
| | | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| # A2 alt | Temperature Reverse Bias | rated reverse voltage ^[1] | 1000 hours | 116 | 5240 | 0 | | |
| | | MIL-STD-750 Method 1037 | | | | | | |
| | IOL | ton = toff, devices powered to insure ΔTj = | | | | | | |
| # A5 | Intermittent Operating Life | 100 °C for 15000 cycles | 1000 hours | 116 | 5240 | 0 | | |
| | BCU | | | | | | | |
| | RSH | JESD22-A111 | | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | n.a. | n.a. | n.a. | | |
| # C10 | SD Solderability | J-STD-002 | | 86 | 2580 | 0 | | |
| # CIU | Solder ability | 5 515 002 | | 00 | 2000 | U | | |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------------------------------|----------|---------|--------------------|------------|
| Nexperia DHAM | Small Signal Bipolar Transistor | 18680 | 0 | 0,23 | 4,40E+09 |

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com